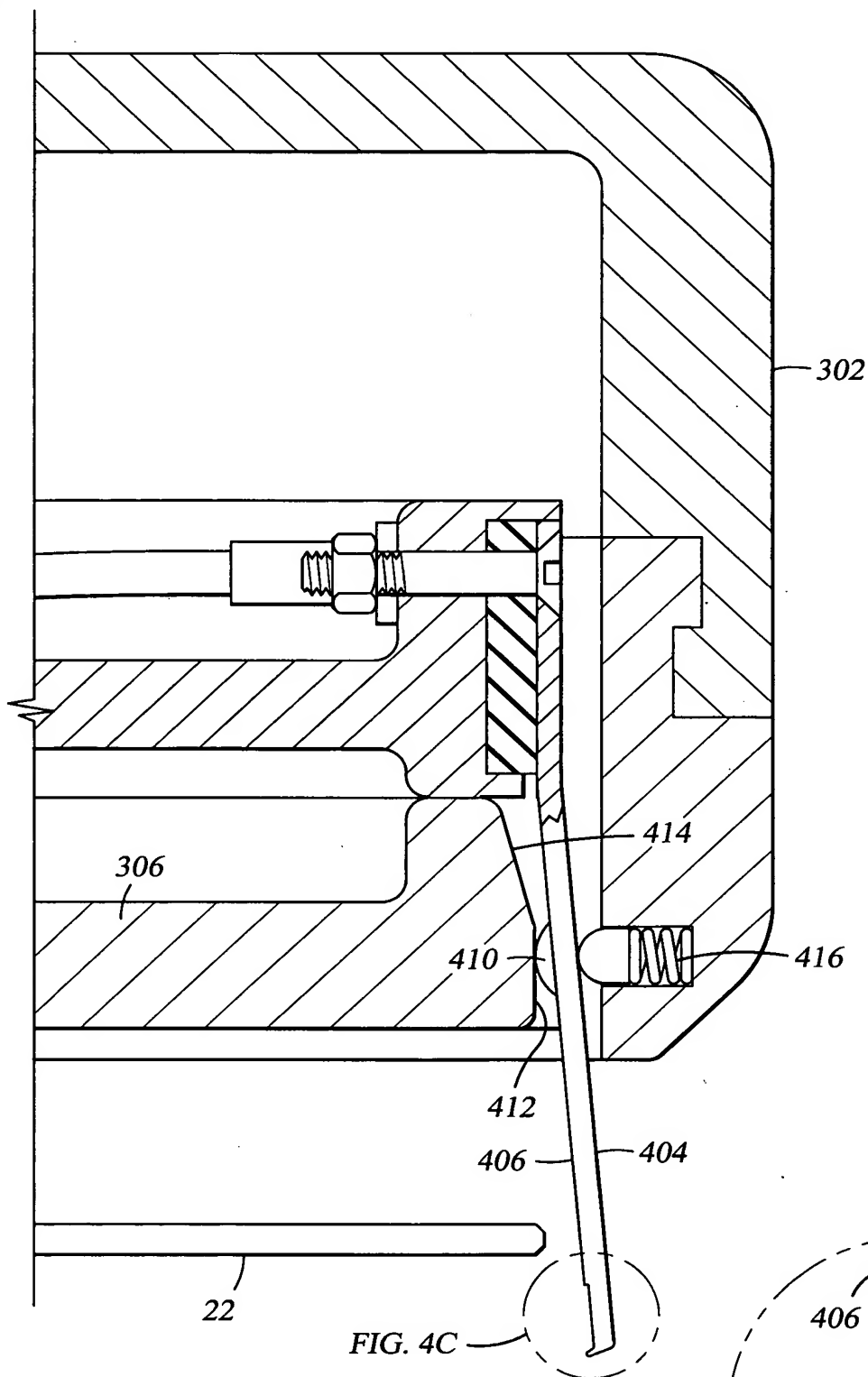
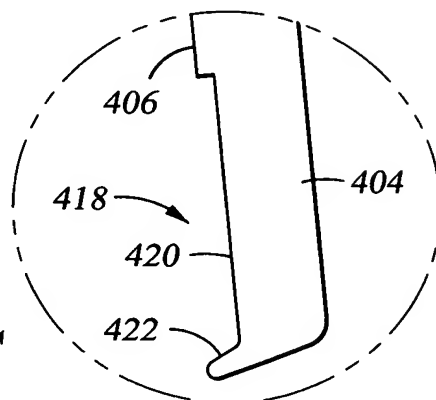


ATTY DKT. No.: **AMAT/5614.D1/CMP/CMP/RKK**  
U.S. SERIAL No.: **10/792,069** CONF. No.: 4228  
FILED: **MARCH 3, 2004**  
APPLICANT: **APPLIED MATERIALS, INC.**  
TITLE: **INTEGRATED MULTI-STEP GAP FILL AND FEATURE  
PLANARIZATION FOR CONDUCTIVE MATERIALS**  
INVENTOR: **HSU, ET AL.**  
**REPLACEMENT DRAWINGS** **PAGE 5 of 15**

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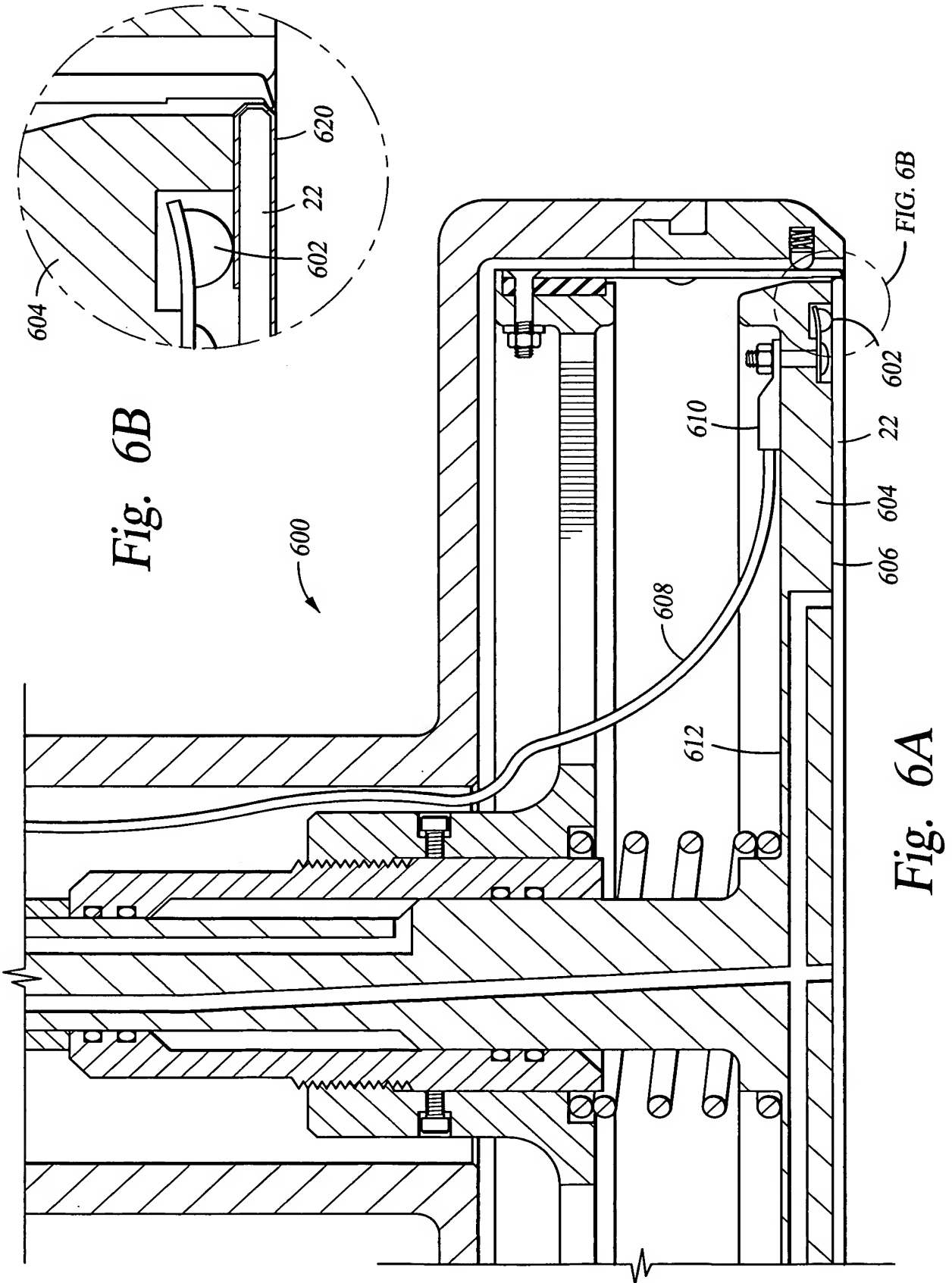


*Fig. 4B*



*Fig. 4C*

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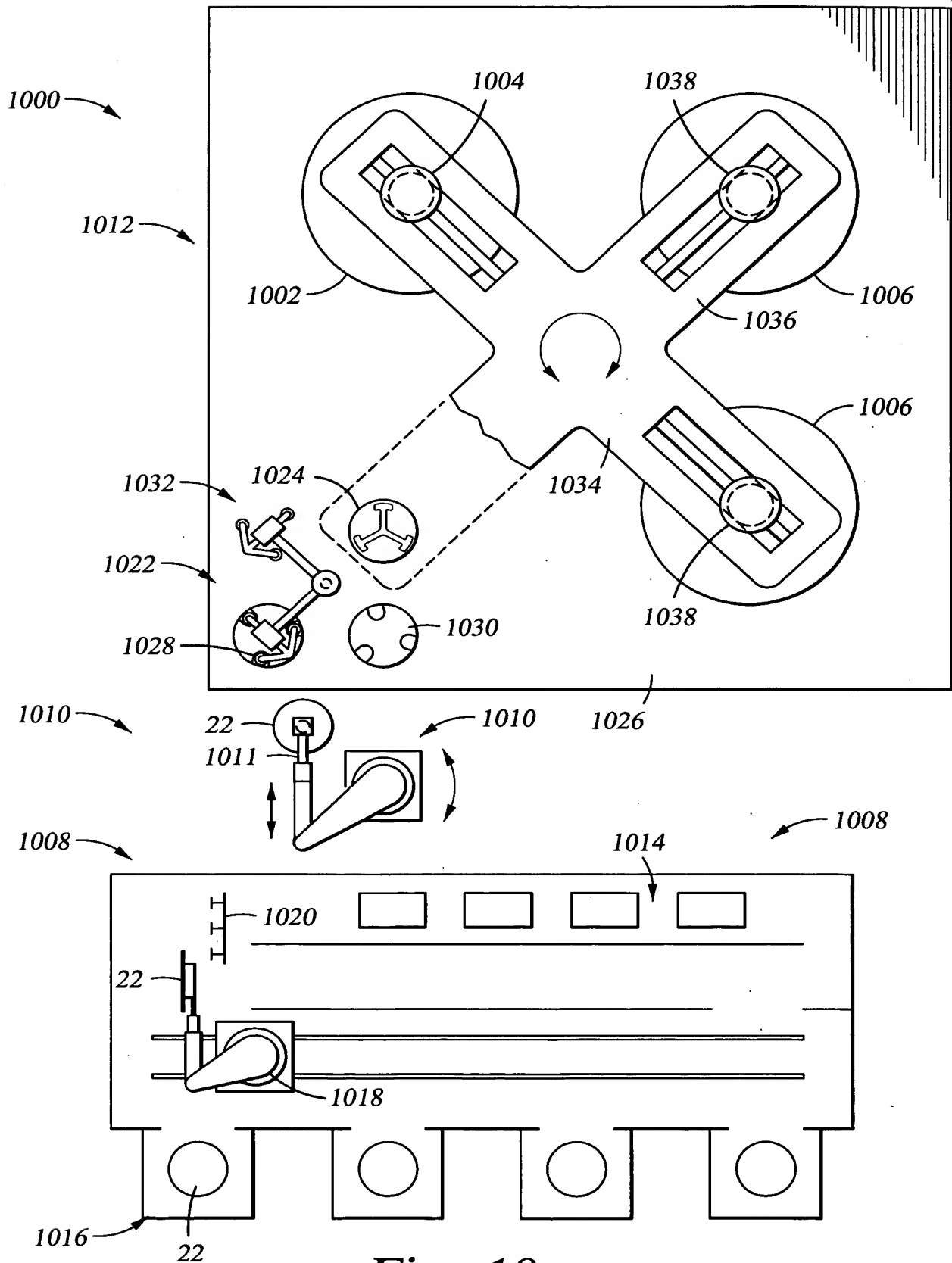


Fig. 10